
Replacing TIOL111x with CCE4503

Abstract

This document contains all changes that might be necessary to replace the TIOL111x with the CCE4503.

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Introduction

Package size

The package size of the CCE4503 and the TIOL111x is slightly different (see Figure 1).

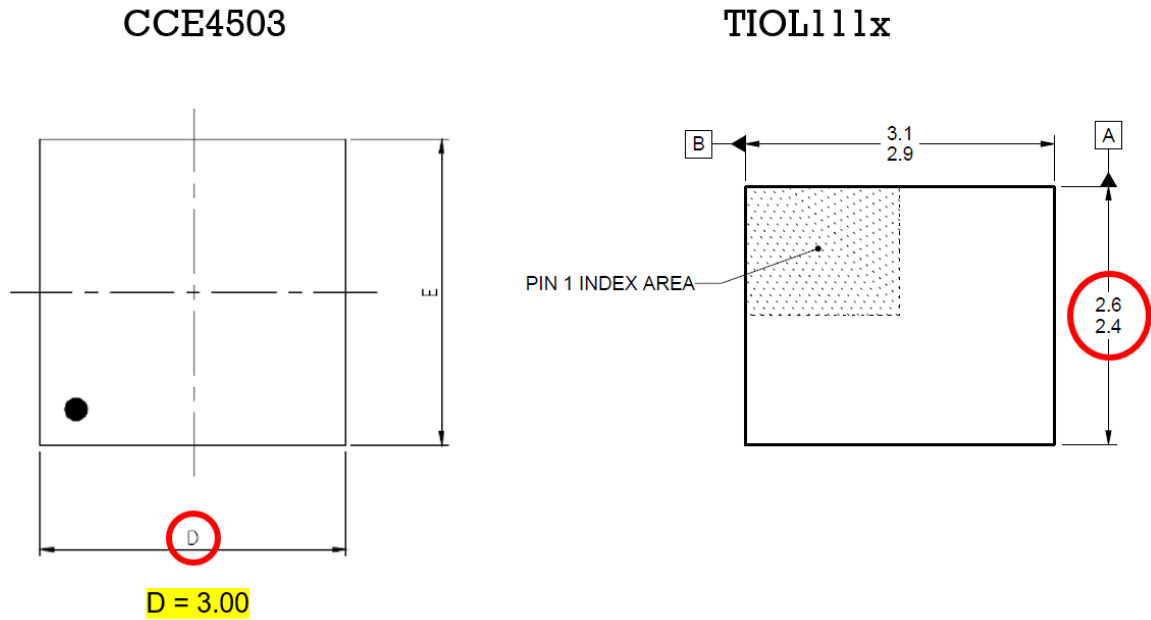


Figure 1: Package size comparison (in mm)

The CCE4503 has a package size of 3 mm x 3 mm while the TIOL111x (see References [2]) has a package size of 3 mm x 2.5 mm. This difference needs to be considered regarding the PCB layout. This does not affect the pitch between the pins.

Footprint change

Since the footprint of the TIOL111x and the CCE4503 have slightly differences it might be necessary to adapt the footprint on the PCB.

The difference is shown in the following figure.

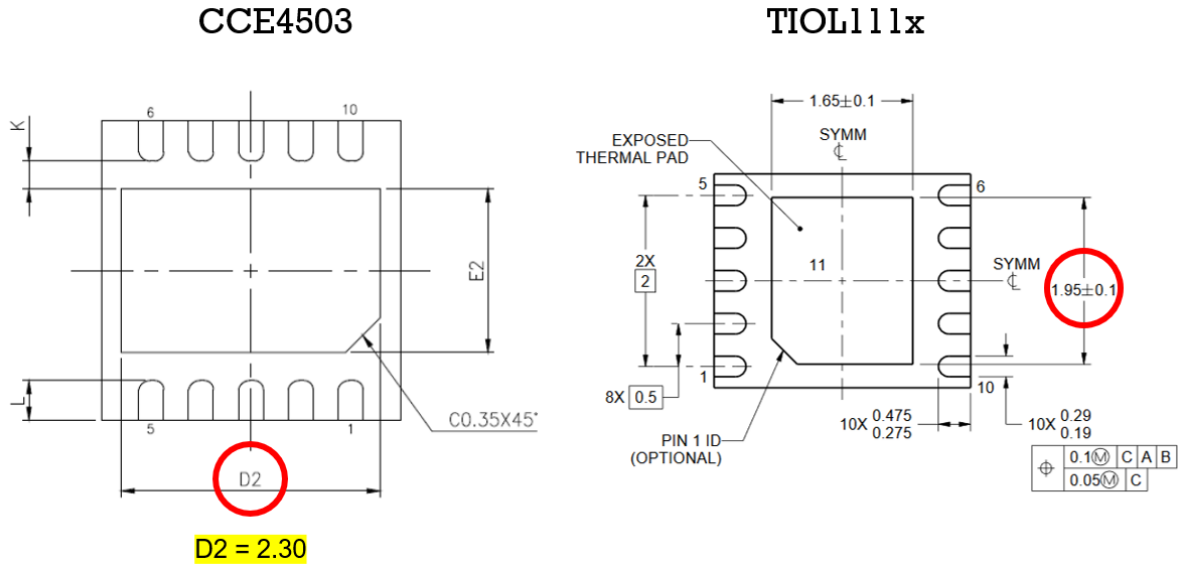


Figure 2: Footprint comparison (in mm)

The CCE4503 has an exposed pad length of 2.30 mm while the TIOL111x (see References [2]) has an exposed pad length of 1.95 mm. This difference needs to be considered regarding the PCB layout.

Revision History

Revision	Date	Description
3	28-Jan-2022	Rebrand
2	10-Dec-2020	Added package size comparison
1	01-Dec-2020	Initial version.

References

- [1] CCE4503, Datasheet, Dialog Semiconductor.
- [2] TIOL111x, Datasheet, Texas Instruments.

Status Definitions

Status	Definition
DRAFT	The content of this document is under review and subject to formal approval, which may result in modifications or additions.
APPROVED or unmarked	The content of this document has been approved for publication.

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